



深圳市高信技术有限公司

SPECIFICATION FOR LCD MODULE

Customer : _____

Customer P/N _____

Model No. : GXTQ102-I4018E30A-05

Version : V00

Date : 2026/05/29

Final Approval by Customer

LCM Machinery OK ☐	Checked By	
LCM Display OK ☐	Checked By	
LCM NG ☐ LCM OK ☐	Approved By	

ShenZhen GX Confirmed :

DESIGN	CHECK	APPROVAL

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	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification		PAGE 3 OF 22

Table of contents

1.0	General Description.....	4
2.0	Absolute Maximum Ratings.....	5
3.0	Optical Characteristics.....	6
4.0	Power On/Off Sequence.....	9
5.0	Electrical Characteristics.....	11
6.0	Reliability Test Items.....	17
7.0	Interface Pin Connection.....	18
8.0	Outline Dimension.....	20
9.0	Package specification.....	21
10.0	General Precaution.....	22

	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification	PAGE 4 OF 22	

1.0 General description

1.1 Introduction

TQ102-I4018E30A-00 is model a color active matrix thin film transistor (TFT) liquid crystal display (LCD) that uses amorphous silicon TFT as a switching device. This model is composed of a TFT LCD panel, a driving circuit and a back light system. This TFT LCD has a10.25 (3:8) inch diagonally measured active display area with FHD(720 horizontal by 1920 vertical pixel array) resolution. The TFT-LCD panel used for this module is adapted for a low reflection and higher color type.

1.2 Features

- 4 lanes MIPI Interface
- Data enable signal mode
- 8-bit color depth,display 16.7M colors
- Low driving voltage and low power consumption
- ROHS Compliant

1.3 General information

Item		Specification	Unit	Remarks
Outline Dimension		101.27(H) x 261.15(V) x 6.87(typ)	mm	
Display area		91.368(W) x243.648(H)	mm	
Number of Pixel		720(H) x RGB x 1920(V)	pixels	
Pixel pitch		0.1269(H) x 0.1269(V)	mm	
Pixel arrangement		Pixels RGB Vertical Stripe		
Display mode		Normally Black		
Sensor Pattern Type		In-Cell		
Touch Channel (T*R)		16x45		
Weight		TBD (Typ.)	gram	
Back-light		Single LED (Side-Light type)		
Power Consumption	B/L System	TBD	watt	
Driver IC		JD9366TC		*Using IC
Polarizer : zhuyou		Up: 0° Down 90°	pcs	

1.4 Mechanical Information

Item		Min.	Typ.	Max.	Unit
Module Size	Horizontal(H)	101.07	101.27	101.47	mm
	Vertical(V)	261.35	261.15	260.95	mm
	Depth(D)	6.67	6.87	7.07	mm

	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification		PAGE 5 OF 22

2.0 ABSOLUTE MAXIMUM RATINGS

2.1 Electrical Absolute Rating (GND=AGND=0V)

Parameter	Symbol	Spec.			Unit	Note
		Min.	Typ.	Max.		
Interface Supply Voltage	IOVCC	-0.3	-	+1.95	V	
Logic Supply Voltage	VCI	-0.3	-	+1.95	V	
Analog Supply Voltage	VCIP	-0.3	-	+3.3	V	
High speed interface Supply Voltage	VCCH	-0.3	-	+1.95	V	
Positive Voltage input	VSP	-0.3	-	+6.3	V	
Negative Voltage input	VSN	0	-	-6.3	V	
Power Supply Voltage	VGH	-0.3	-	+20	V	
Power Supply Voltage	VGL	0	-	-18	V	
Operation Temperature	TOPR	-20	-	+70	°C	
Storage Temperature	TSTG	-30	-	+80	°C	

Note: (1) All of the Voltages listed above are with respect to GND=0V.

2.2 TFT LCD Power Supply Voltage

Parameter	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	IOVCC	1.65	1.8	1.95	V
	VCI	-	3.3	-	V
	RST	1.65	1.8	1.95	V

	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification		PAGE 21 OF 22

2.3 Back-light Unit

Parameter	Symbol	Min	Typ	Max.	Unit	Note
LED Current	I _L	-	180	210	mA	Ta=25℃
LED Voltage	V _L	-	19.2	-	V	Ta=25℃
LED Life-time	h	20000	-	-	V	Ta=25℃ , If=20mA

2.4 Environment Absolute Rating

Item	Symbol	Min.	Max.	Unit	Note
Operating Temperature	Topa	-20	70	℃	
Storage Temperature	Tstg	-30	80	℃	

	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification		PAGE 7 OF 22

3.0 OPTICAL CHARACTERISTICS

3.1 Optical Specifications

Item	Symbol	Temp	Condition	Min	Typ	Max	Unit	Remark
Viewing Angle range	Horizontal	θ_{L}	CR > 10	80	85	--	Deg	Note (1,2)
		θ_{R}		80	85			
	Vertical	θ_{U}		80	85	--	Deg	
		θ_{D}		80	85			
Luminance Contrast ratio		CR	$\theta = 0^{\circ}$	800	1000	--	--	Note (1,2)
Brightness		YL		350	400	--	Cd/cm2	Note (4,5)
Transmittance (with Polarizer)		T(%)	$\theta = 0^{\circ}$	3.9	4.32	--	%	
Transmittance (without Polarizer)		T(%)	$\theta = 0^{\circ}$	13.3	14.77	--	%	
Color Gamut (C light)				65	70	--	%	
Reproduction of color (C-light)	White	Xw	$\theta = 0^{\circ}$	-0.02	0.311	+0.02		Note (1,4) Measurin g with normal polarizer Reference Only
		Yw			0.334			
	Red	Rx			0.652			
		Ry			0.326			
	Green	Gx			0.284			
		Gy			0.579			
	Blue	Bx			0.137			
		By			0.085			
Response Time (Rising + Falling)	Trt		Ta= 25° C $\theta = 0^{\circ}$	--	25	30	ms	Note (1,3)
Opetical View Direction			ALL					Note (1)

3.2 Measuring Condition

Measuring surrounding: dark room
Ambient temperature: 25±2℃
15min. warm-up time.

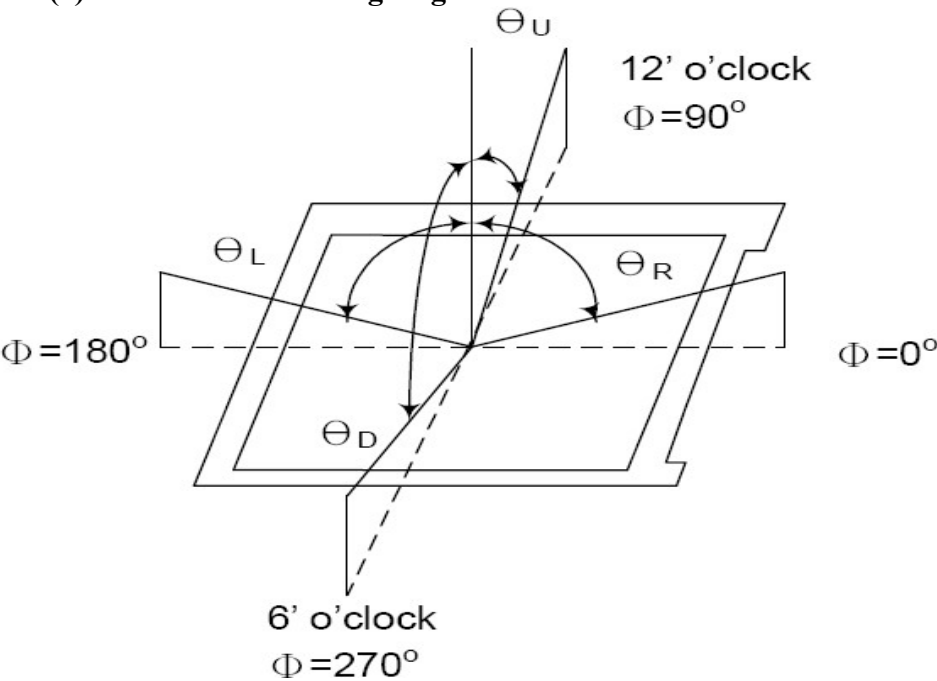
3.3 Measuring Equipment

FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity

	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification	PAGE 8 OF 22	

and BM-7 for other optical characteristics. Measuring spot size: 20 ~ 21 mm

Note (1) Definition of Viewing Angle :

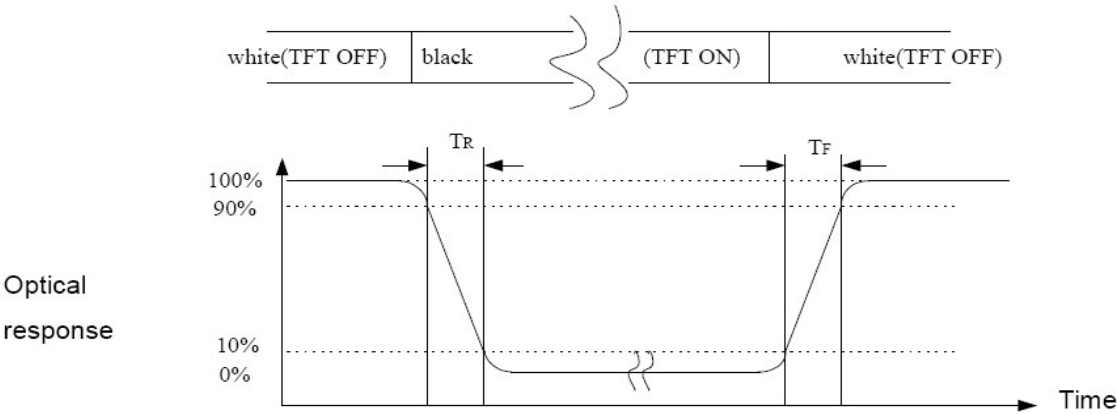


Note (2) Definition of Contrast Ratio (CR):

Measured at the center point of panel

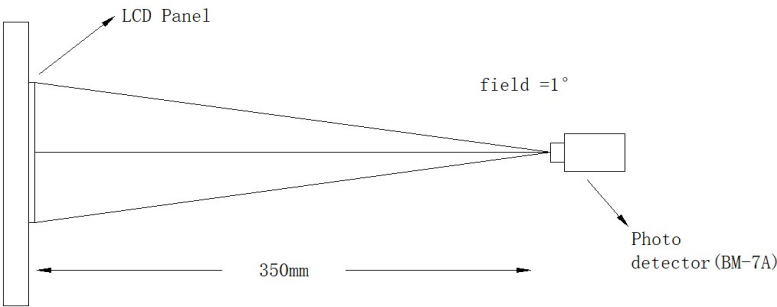
$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note (3) Definition of Response Time: Sum of TR and TF

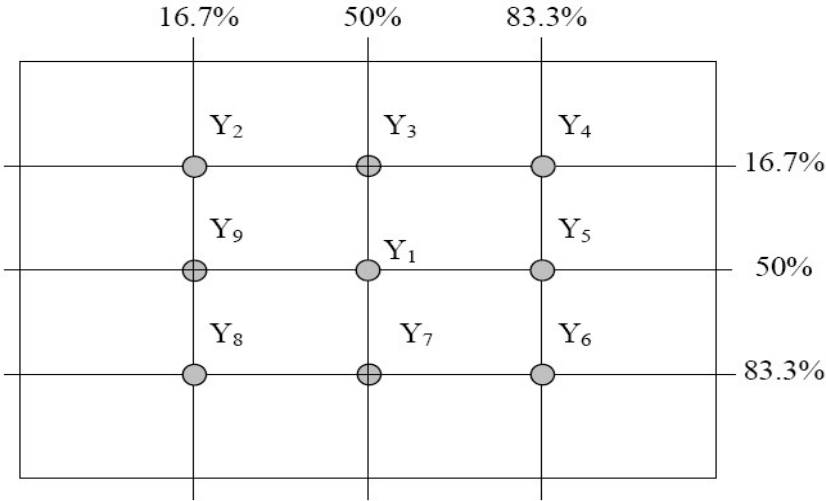


	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification		PAGE 9 OF 22

Note (4) Definition of optical measurement setup



Note (5) Definition of brightness uniformity



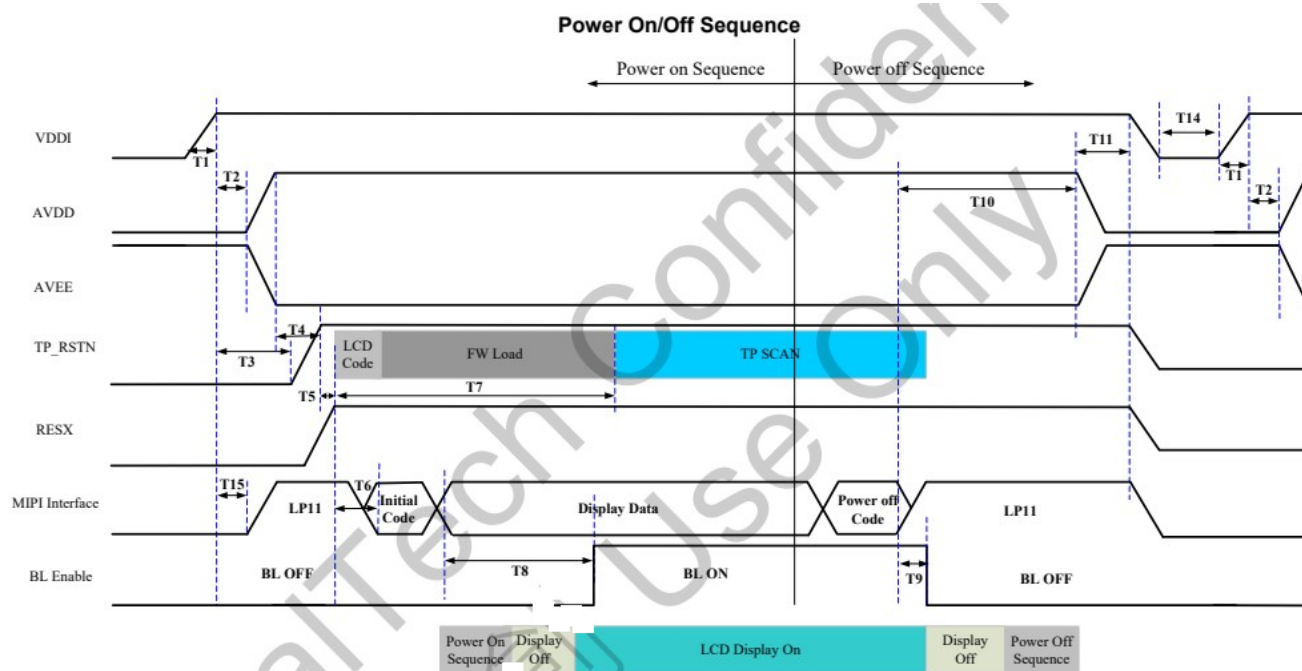
$$\text{Luminance uniformity} = \frac{(\text{Min Luminance of 9 points})}{(\text{Max Luminance of 9 points})} \times 100\%$$

	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification	PAGE 10 OF 22	

4.0 Power On/Off Sequence

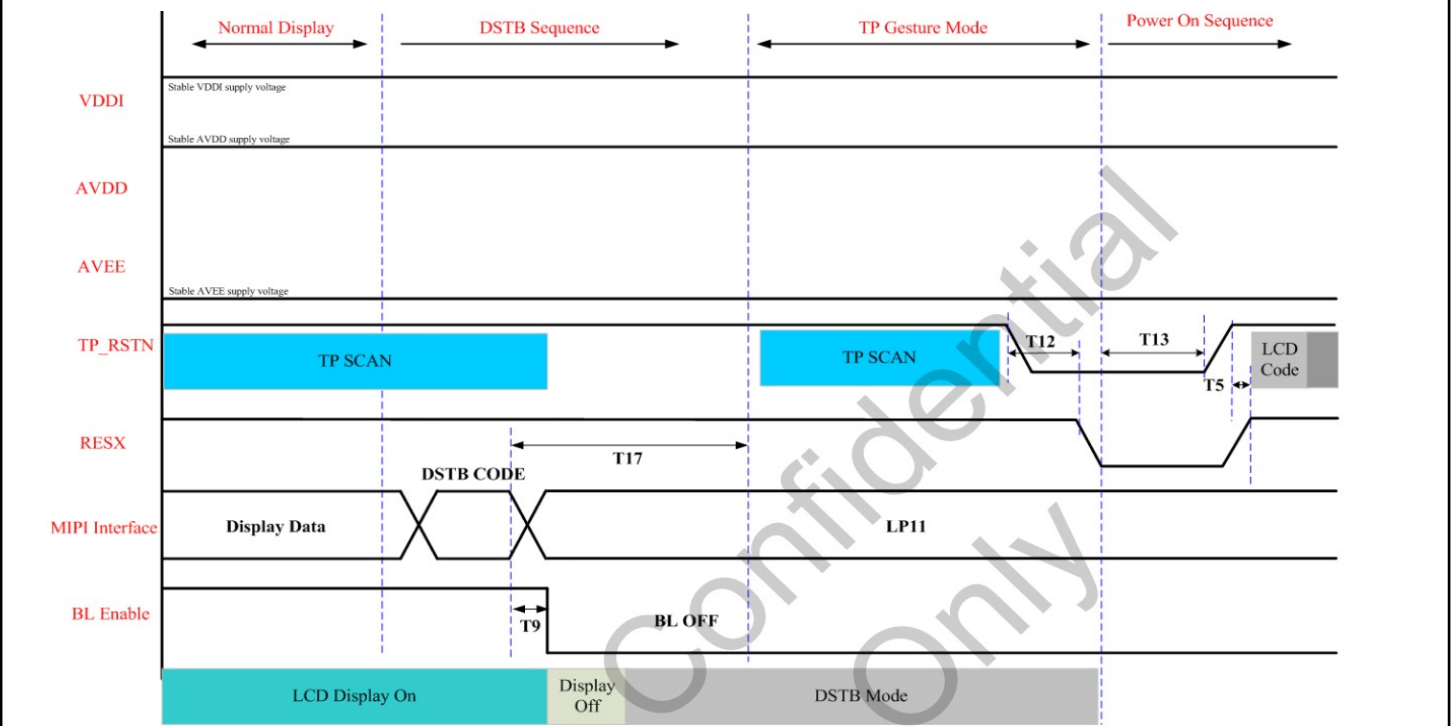
To prevent the device damage from latch up, the power on/off sequence shown Below must be followed.

1. There will be no damage to the display module if the power sequences are not met.
2. There will be no abnormal visible effects on the display panel during the Power On/Off sequences.
3. There will be no abnormal visible effects on the display between end of Power On sequence and before receiving Sleep Out command.
Also between receiving Sleep In command and Power Off sequence.
4. RESX and TP_RSTN must be held stably by host during Power On Sequence, otherwise function is not guaranteed.
5. The display module can also initialize and calibrate DSI-CLK +/- and DSI-D0 +/- lanes within 5ms after LP-11 (Clock and Data Channels),
VDDI are applied and H/W Reset is not active (5ms is as same as the Reset Cancelling Time).
6. During Power off, VDDI can be powered down 5ms after AVDD/AVVEE power down if LCD in Sleep-In Mode.
7. During Abnormal power dropping, VDDI can start power down 5ms after AVDD/AVEE power down.
8. BL Enable timing is for reference only and not restricted (T8/T9).

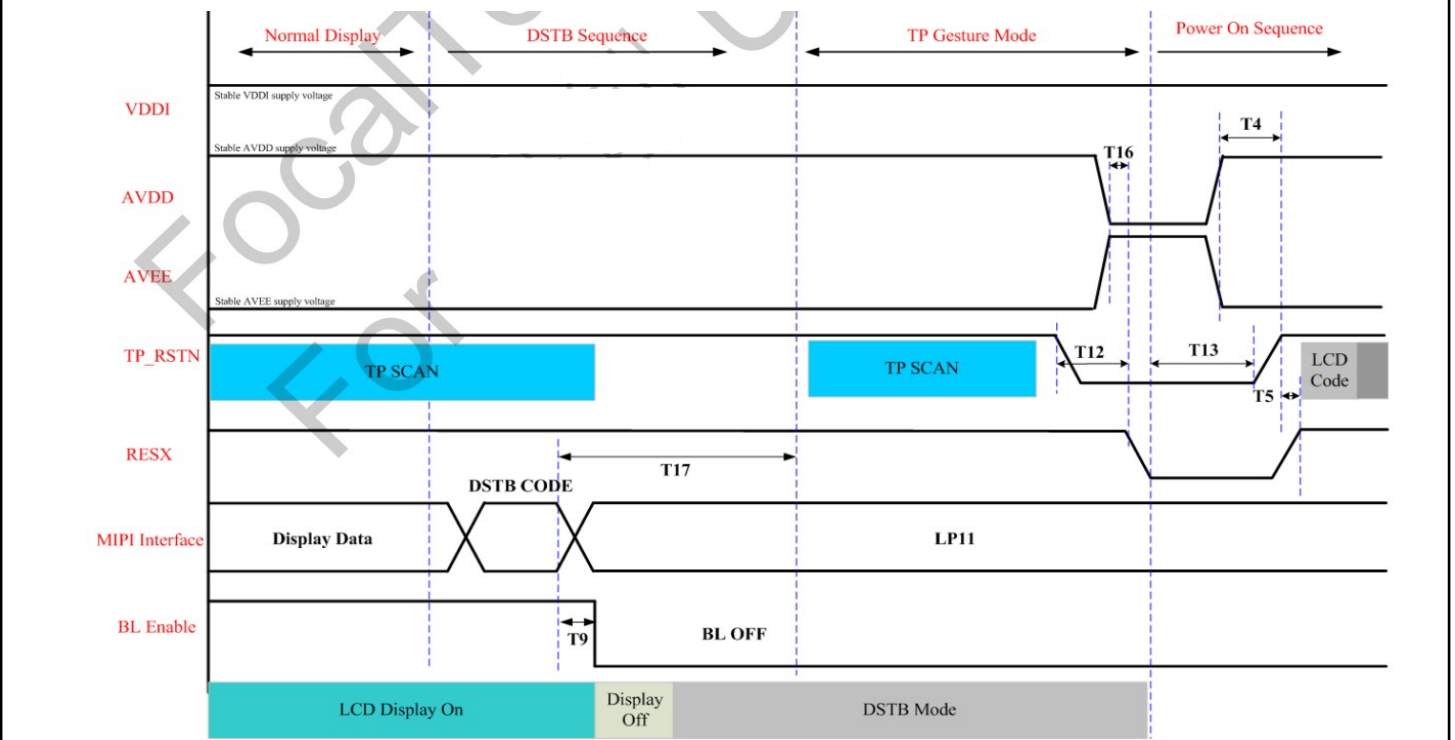


	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification	PAGE 11 OF 22	

TP Gesture Mode Exit Sequence



TP Gesture Mode Exit Sequence with AVDD/AVEE disabled



	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification	PAGE 12 OF 22	

Power On / Off Sequence Timing				
Parameter	Description	Min.	Max.	Unit
T1	Rise time from 0.1VDDI to 0.9VDDI	0	5	mS
T2	AVDD/AVEE rise after VDDI power on	3		mS
T3	TP reset time after VDDI power on	5		mS
T4	TP Reset release time after AVDD power on	100		uS
T5	TP Reset release to LCD Reset release	0		mS
T6	FLASH download LCD code after LCD Reset	35		mS
T7	LCD Reset release to TP SCAN Start (Single Chip application)	150		mS
	LCD Reset release to TP SCAN Start (Cascade application)	350		mS
T8	LED On after Initial Code	150		mS
T9	LED Off after power off code	50		mS
T10	AVDD/AVEE power down after power off code	150		mS
T11	VDDI power down after AVDD/AVEE power down	5		mS
T12	TP reset time before LCD reset	5		mS
T13	RESX reset falling to TP reset release	5	120	mS
T14	VDDI rise again after previous VDDI powered down	50		mS
T15	MIPI signals start (Hi-Z/GND to LP11) after VDDI power on	3		mS
T16	AVDD/AVEE power down to LCD reset	1		mS
T17	TP Gesture mode start after power off command code	150		mS
Trf	2 nd LCD Reset time after TP_RST assert	5		mS
Trl	2 nd LCD/TP Reset overlap time	5		mS
Trw	TP Reset High Level Width before 2 nd Reset		10	mS

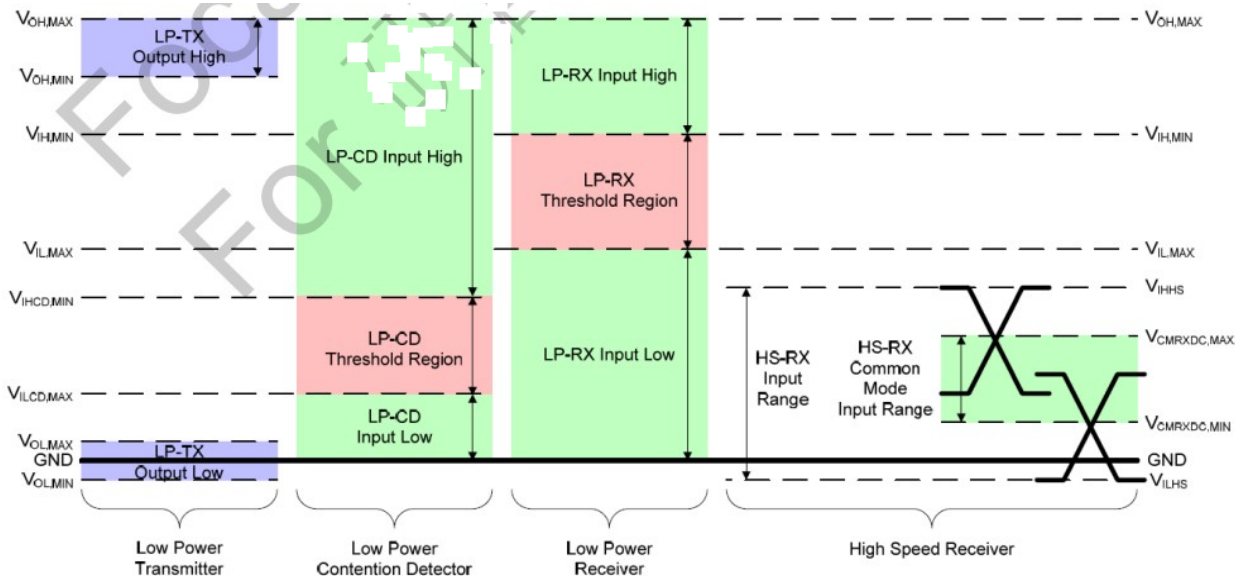
	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification	PAGE 13 OF 22	

5.0 ELECTRICAL CHARACTERISTICS

5.1 DC characteristics for MIPI-DSI

(AVDD = 5.0V~6.5V,AVEE = -5.0V~-6.5V,VDDI = 1.65V~1.95V, Ta = -30°C ~ 70°C)

Parameter	Symbol	Conditions	Specification			Unit
			MIN	TYP	MAX	
Power supply voltage for MIPI Interface						
Power supply voltage for MIPI interface	VDDAM	-	1.65	1.8	1.95	V
	LVDSVDD	-	1.125	1.3	1.5	V
LPDT Input Characteristics						
Pad signal voltage range	VI	-	-50	-	1350	mV
Ground Shift	VGND _{SH}	-	-50	-	50	mV
Logic 0 input threshold	VIL	-	0	-	550	mV
Logic 1 input threshold	VIH	-	880	-	LVDSVDD	mV
Input hysteresis	VHYST	-	25	-	-	mV
LPDT Output Characteristics						
Output low level	VOL	-	-50	-	50	mV
Output high level	VOH	-	1.1	1.2	1.3	V
Logic 1 contention threshold	VIH _{CD} ,MIN	-	450	-	LVDSVDD	mV
Logic 0 contention threshold	VIL _{CD} ,MAX	-	0	-	200	mV
Output impedance of LPDT	ZOLP	-	80	100	125	ohm
Hi-speed Input/Output Characteristics						
Single-end input low voltage	VIL _{HS}	-	-40	-	-	mV
Single-end input high voltage	VIH _{HS}	-	-	-	460	mV
Single-end threshold for HS termination enable	VTERM-EN	-	-	-	450	mV
Differential input low threshold	VID _{TL}	-	-70	-	-	mV
Differential input high threshold	VID _{TH}	-	-	-	70	mV
Common mode voltage	VCM _{RXDC}	-	70	-	330	mV
Differential input impedance	ZID	-	80	100		ohm



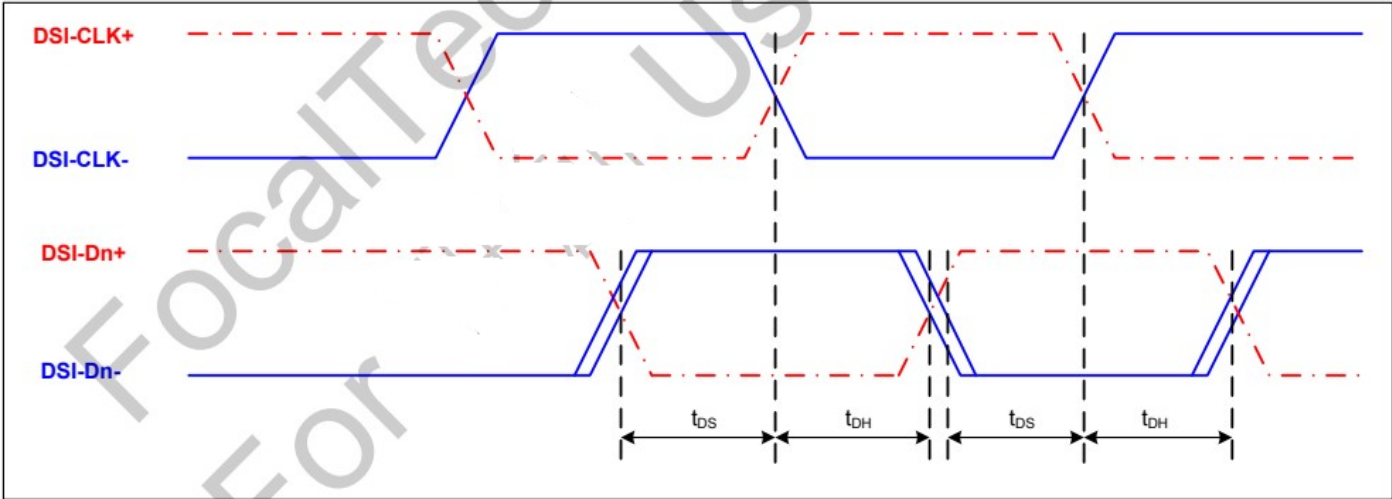
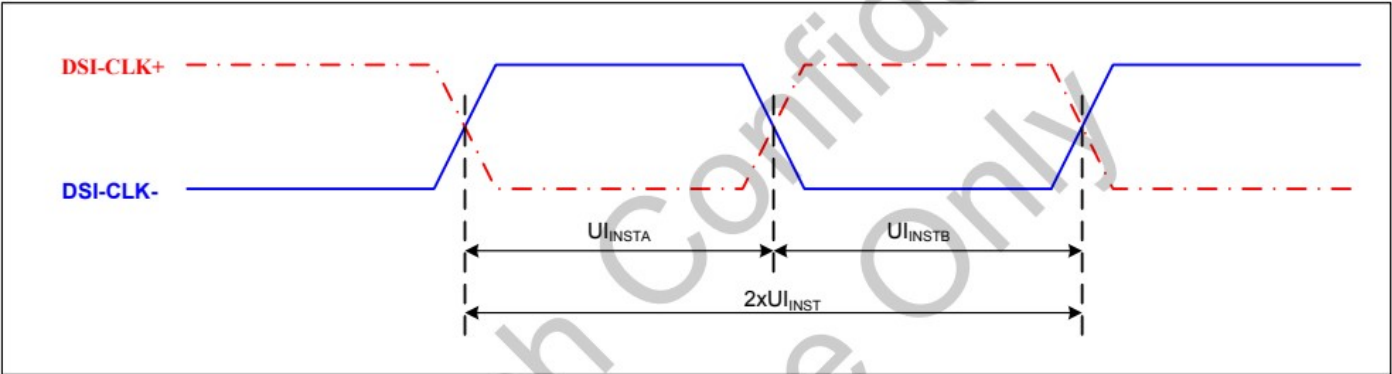
	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification		PAGE 14 OF 22

5.2 AC characteristics

MIPI-DSI characteristics

High speed mode

Parameter	Symbol	Parameter	Specification			Unit
			MIN	TYP	MAX	
High Speed Mode						
DSI-CLK+/-	2xUI _{INST}	Double UI instantaneous	2	-	25	ns
DSI-CLK+/-	UI _{INSTA} , UI _{INSTB}	UI instantaneous Halfs	1	-	12.5	ns
DSI-Dn+/-	t _{DS}	Data to clock setup time	0.15	-	-	UI
DSI-Dn+/-	t _{DH}	Data to clock hold time	0.15	-	-	UI
DSI-CLK+/-	t _{DRTCLK}	Differential rise time for clock	150	-	0.3UI	ps
DSI-Dn+/-	t _{DRTDATA}	Differential rise time for data	150	-	0.3UI	ps
DSI-CLK+/-	t _{DFTCLK}	Differential fall time for clock	150	-	0.3UI	ps
DSI-Dn+/-	t _{DFTDATA}	Differential fall time for data	150	-	0.3UI	ps



	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification		PAGE 15 OF 22

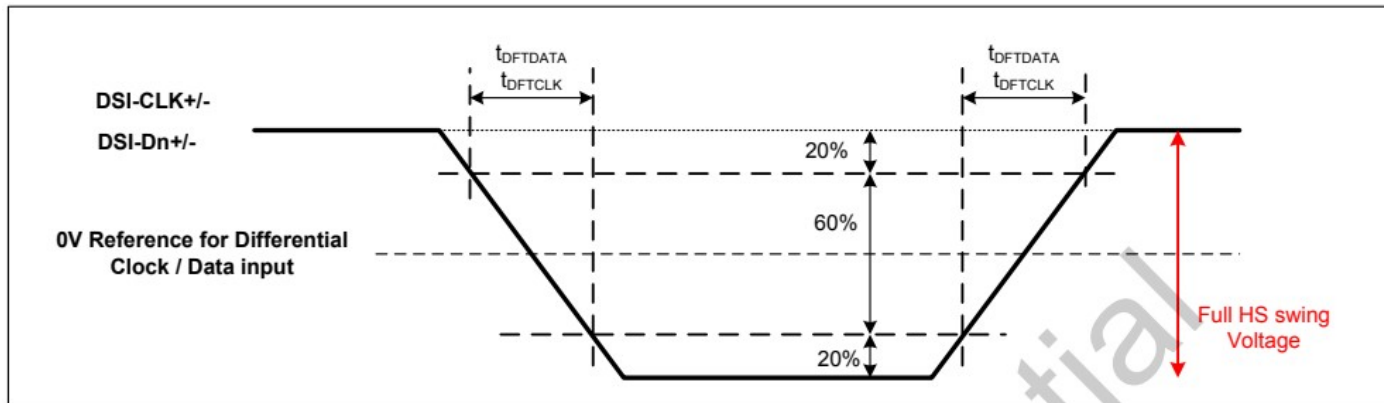


Figure: AC characteristics for MIPI-DSI High speed mode

Low power mode

Parameter	Symbol	Parameter	Specification			Unit
			MIN	TYP	MAX	
Low Power mode						
DSI-D0+/-	T _{LPXM}	Length of LP-00, LP-01, LP-10 or LP-11 periods MPU Display Module	50	-	-	ns
DSI-D0+/-	T _{LPXD}	Length of LP-00, LP-01, LP-10 or LP-11 periods Display Module MPU	58	-	-	ns
DSI-D0+/-	T _{TA-SURED}	Time-out before the MPU start driving	T _{LPXD}	-	2XT _{LPXD}	ns
DSI-D0+/-	T _{TA-GETD}	Time to drive LP-00 by display module	5XT _{LPXD}	-	-	ns
DSI-D0+/-	T _{TA-GOD}	Time to drive LP-00 after turnaround request - MPU	4XT _{LPXD}	-	-	ns
DSI-D0+/-	Ratio T _{LPX}	Ratio of T _{LPXM} / T _{LPXD} between MCU and display module	2/3	-	3/2	-

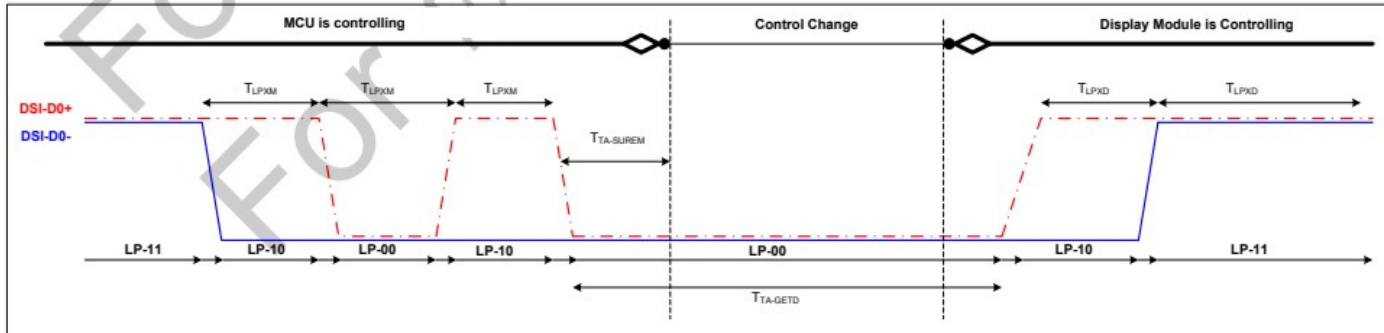


Figure: BTA from the MCU to the Display Module

PRODUCT GROUP

REV

ISSUE DATE

TFT- LCM PRODUCT

P0

2025.07.18

SPEC. NUMBER

SPEC . TITLE
10.25LCM+CG Product Specification

PAGE
17 OF 22

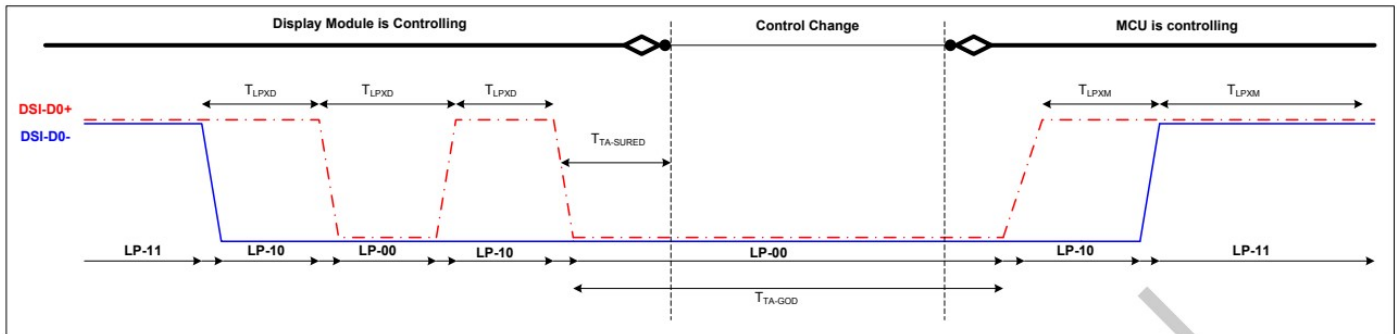


Figure: BTA from the Display Module to the MCU

Bursts

Parameter	Symbol	Parameter	Specification			Unit
			MIN	TYP	MAX	
High Speed Data Transmission Bursts						
DSI-Dn+/-	T _{LPX}	Length of any low-power state period	50	-	-	ns
DSI-Dn+/-	T _{HS-PREPARE}	Time to drive LP-00 to prepare for HS transmission	40ns + 4UI	-	85ns + 6UI	ns
DSI-Dn+/-	T _{HS-PREPARE} + T _{HS-ZERO}	T _{HS-PREPARE} + time to drive HS-0 before the sync sequence	145ns + 10UI	-	-	ns
DSI-Dn+/-	T _{D-TERM-EN}	Time to enable Data Lane receiver line termination measured from when Dn crosses V _{IL(max)}	Time for Dn to reach V _{TERM-EN}	-	35ns + 4UI	ns
DSI-Dn+/-	T _{HS-SKIP}	Time-out at RX to ignore transition period of EoT	40	-	55ns + 4UI	ns
DSI-Dn+/-	T _{HS-TRAIL}	Time to drive flipped differential state after last payload data bit of a HS transmission burst	max (8UI, 60ns+4UI)	-	-	ns
DSI-Dn+/-	T _{HS-EXIT}	Time to drive LP-11 after HS burst	100	-	-	ns
DSI-Dn+/-	T _{EoT}	Time from start of T _{HS-TRAIL} period to start of LP-11 state	-	-	105ns + 12UI	ns

	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification	PAGE 17 OF 22	

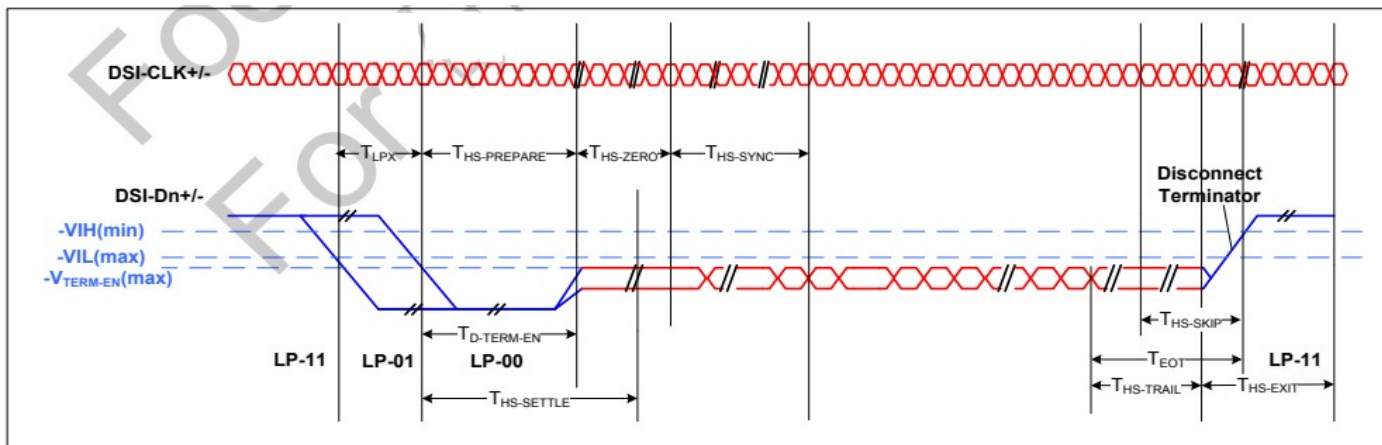


Figure: High Speed Data Transmission Bursts

6.0 Reliability test items

Test Item	Test Conditions	Notes
High temperature Operation	Ta= +70°C, 96hrs	
Low temperature Operation	Ta= -20°C, 96hrs	
High Temperature Storage	Ta= +80°C, 96hrs	
Low Temperature Storage	Ta= -30°C, 96hrs	
Humidity Test	60°C ,Humidity 90% ,96hrs	
Thermal Shock Test	-20°C,30min ~ +70°C,30min (30 cycle)	
Vibration Test(Packing)	Sine Wave 1.04G, 5~500Hz, XYZ 30min/each direction	
Static Electricity	Half-Sine, 100G, 6ms, ±XYZ, 3 cycle	

	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification		PAGE 18 OF 22

7.0 INTERFACE PIN CONNECTION

LCM of interface Pin name

Terminal No.	Symbol	I/O	Functions
1	GND	P	Ground.
2	MIPI_D0+	I	Positive MIPI differential data inputs0+.
3	MIPI_D0-	I	Negative MIPI differential data inputs0-.
4	GND	P	Ground.
5	MIPI_D1+	I	Positive MIPI differential data inputs1+.
6	MIPI_D1-	I	Negative MIPI differential data inputs1-.
7	GND	P	Ground.
8	MIPI_CLK+	I	Positive MIPI differential clock inputs.
9	MIPI_CLK-	I	Negative MIPI differential clock inputs.
10	GND	P	Ground.
11	MIPI_D2+	I	Positive MIPI differential data inputs2+.
12	MIPI_D2-	I	Negative MIPI differential data inputs2-.
13	GND	P	Ground
14	MIPI_D3+	I	Positive MIPI differential data inputs3+.
15	MIPI_D3-	I	Negative MIPI differential data inputs3-.
16	GND	P	Ground.
17	GND	P	Ground.
18	NC	O	No connection.
19	NC	O	No connection.
20	NC	O	No connection.
21	NC	O	No connection.
22	NC	O	No connection.
23	NC	O	No connection.
24	RESET	I	Global reset pin, active low. (Default pull High). (+3.3V)
25	GND	P	Ground.
26	NC	O	No connection.
27	GND	P	Ground.
28	LED-K	I	LED cathode.
29	LED-K	I	LED cathode.
30	GND	P	Ground.
31	NC	O	No connection.

	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification		PAGE 19 OF 22

32	GND	P	Ground.
33	GND	P	Ground.
34	NC	O	No connection.
35	LED-A	I	LED anode.
36	LED-A	I	LED anode.
37	GND	P	Ground.
38	VCI	I	Power supply for analog circuit. (+3.3V)
39	VCI	I	Power supply for analog circuit. (+3.3V)
40	NC	O	No connection.

Touch of interface Pin name

Terminal No.	Symbol	I/O	Functions
1	TP_SCL	I	Touch screen clock input for I2C interface. (+3.3V)
2	TP_SDA	I	Touch screen data input I2C interface. (+3.3V)
3	VCC	I	Power supply for analog circuit. (+3.3V)
4	TP_RESET	I	Touch circuit reset pin, active low. (Default pull High). (+3.3V)
5	TP_INT	O	Touch screen interrupt line. Interrupt active when the line is low. (+3.3V)
6	GND	P	Ground.

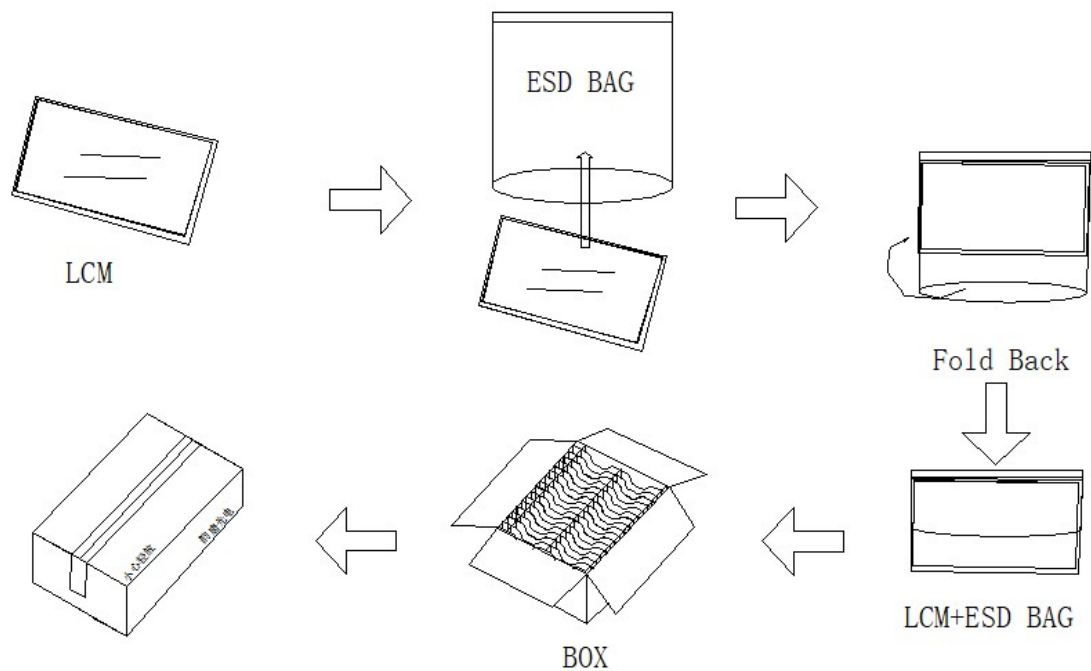
	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification		PAGE 21 OF 22

9.0 Package Specification

9.1 Packing form

LCM Moudle	LCM Qty. in the box	Box size	Note
	TBD pcs/box		

9.2 Packing assembly drawing



	Material	Notice
Box	Corrugated Paper Board	(AB Flute)
Partition/Pad	Corrugated Paper Board	(B Flute)
Corner Pad	Corrugated Paper Board	(AB Flute)
ESD bag	PE	

	PRODUCT GROUP	REV	ISSUE DATE
	TFT- LCM PRODUCT	P0	2025.07.18
SPEC. NUMBER	SPEC . TITLE 10.25LCM+CG Product Specification	PAGE 22 OF 22	

10.0 General precaution

10.36 Use Restriction

This product is not authorized for use in life supporting systems, aircraft navigation control systems, military systems and any other application where performance failure could be life threatening or otherwise catastrophic.

10.2 Disassembling or Modification

Do not disassemble or modify the module. It may damage sensitive parts inside LCD module, and may cause scratches or dust on the display. YT does not warrant the module, if customers disassemble or modify the module.

10.3 Breakage of LCD Panel

10.3.1.If LCD panel is broken and liquid crystal spills out, do not ingest or inhale liquid crystal, and do not contact liquid crystal with skin.

10.3.2. If liquid crystal contacts mouth or eyes, rinse out with water immediately.

10.3.3. If liquid crystal contacts skin or cloths, wash it off immediately with alcohol and rinse thoroughly with water.

10.3.4. Handle carefully with chips of glass that may cause injury, when the glass is broken.

10.4 Electric Shock

10.4.1. Disconnect power supply before handling LCD module.

10.4.2. Do not pull or fold the LED cable.

10.4.3. Do not touch the parts inside LCD modules and the fluorescent LED's connector or cables in order to prevent electric shock.

10.5 Absolute Maximum Ratings and Power Protection Circuit

10.5.1. Do not exceed the absolute maximum rating values, such as the supply voltage variation, input voltage variation, variation in parts' parameters, environmental temperature, etc., otherwise LCD module may be damaged.

10.5.2. Please do not leave LCD module in the environment of high humidity and high temperature for a long time.

10.5.3. It's recommended to employ protection circuit for power supply.

10.6 Operation

10.6.1 Do not touch, push or rub the polarizer with anything harder than HB pencil lead.

10.6.2 Use fingerstalls of soft gloves in order to keep clean display quality, when persons handle the LCD module for incoming inspection or assembly.

10.6.3 When the surface is dusty, please wipe gently with absorbent cotton or other soft material.

10.6.4 Wipe off saliva or water drops as soon as possible. If saliva or water drops contact with polarizer for a long time, they may causes deformation or color fading.

10.6.5 When cleaning the adhesives, please use absorbent cotton wetted with a little petroleum benzine or other adequate solvent.

10.7 Mechanism

Please mount LCD module by using mouting holes arranged in four corners tightly.

10.8 Static Electricity

10.8.1 Protection film must remove very slowly from the surface of LCD module to prevent from electrostatic occurrence.

10.8.2. Because LCD module use CMOS-IC on circuit board and TFT-LCD panel, it is very weak to electrostatic discharge. Please be careful with electrostatic discharge. Persons who handle the module should be grounded through adequate methods.

10.9 Strong Light Exposure

The module shall not be exposed under strong light such as direct sunlight. Otherwise, display characteristics may be changed.

10.360 Disposal

When disposing LCD module, obey the local environmental regulations.